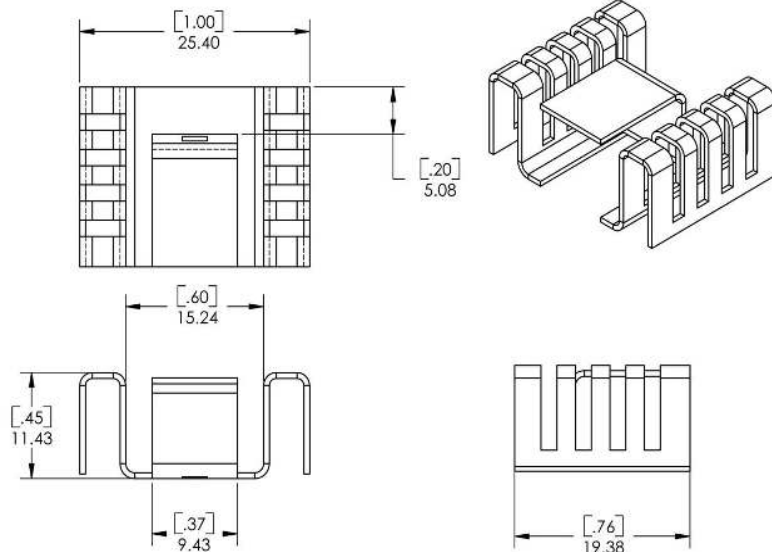
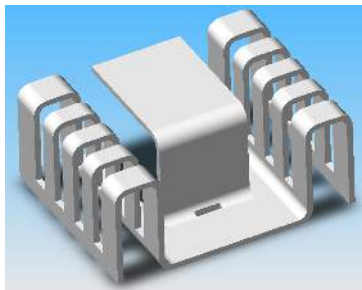


# Board Level Heat Sinks



ThermaFlo

**P/N: 834000T00000 & 8340TRT00000**



## PRODUCT SPECIFICATIONS

- Devices: D2 PAK, TO-263
- Size: 19.4 x 25.4 x 11.4 mm
- Material: Copper, 0.6 mm Thick
- Type: Stamped
- PCB Mounting: Surface Mount Technology
- Finish: Tin Plate
- Package: Bulk or Tape & Reel

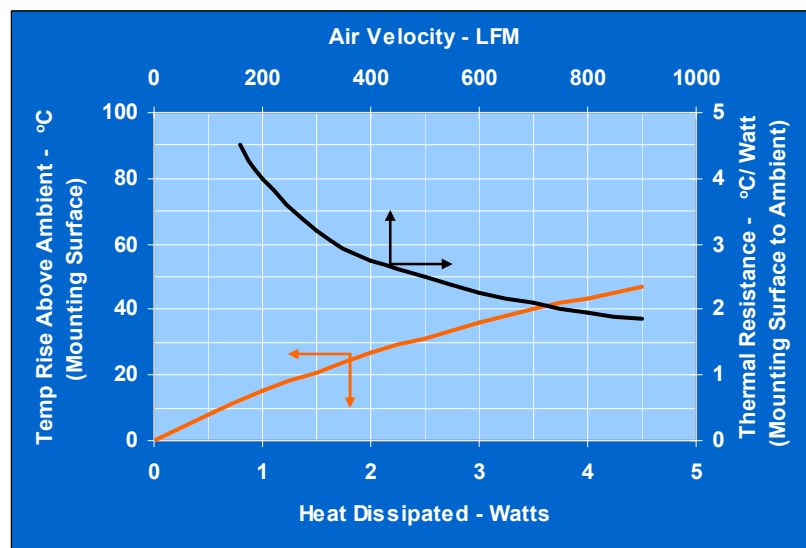
## FEATURES & BENEFITS

- No Hardware Device Attachment
- Direct SMT Contact to PCB
- Solderable Legs
- RoHS Compliant



## CUSTOMIZED HEATSINKS

- Specialized Body Configurations
- Contact Applications Engineering



**D2 PAK, TO-263**

Part Number	Packaging	Notes
834000T00000	Bulk	
8340TRT00000	Tape & Reel	Contact Factory for Tape and Reel Specs

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